TLE42794

Low Dropout Fixed Voltage Regulator

Automotive Power





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TLE42794





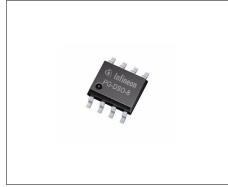
1 Overview

Features

- Output Voltage 5 V ± 2%
- Ouput Current up to 150 mA
- · Very low Current Consumption
- Early Warning
- Power-on and Undervoltage Reset with Programmable Delay Time
- Reset Low Down to V_O = 1 V
- Adjustable Reset Threshold
- Very Low Dropout Voltage
- · Output Current Limitation
- Reverse Polarity Protection
- · Overtemperature Protection
- · Suitable for Use in Automotive Electronics
- Wide Temperature Range from -40 °C up to 150 °C
- Input Voltage Range from -42 V to 45 V
- Green Product (RoHS compliant)
- AEC Qualified

Description

The TLE42794G is a monolithic integrated low dropout voltage regulator, especially designed for automotive applications. An input voltage up to 45 V is regulated to an output voltage of 5.0 V. The component is able to drive loads up to 150 mA. It is short-circuit protected by the implemented current limitation and has an integrated overtemperature shutdown. A reset signal is generated for an output voltage $V_{\rm Q,rt}$ of typically 4.65 V. This threshold can be decreased by an external resistor divider. The power-on reset delay time can be programmed by the external delay capacitor. The additional sense comparator provides an early warning function: Any voltage (e.g. the input voltage) can be monitored, an under-voltage condition is indicated by setting the comparator's output to low. If pull-up resistors are desired at the outputs of the reset and the sense comparator, the TLE42694 with integrated pull-up resistors can be used instead of the TLE42794.



PG-DSO-8



PG-DSO-14



PG-SSOP-14 exposed pad

Туре	Package	Marking
TLE42794G	PG-DSO-8	42794G
TLE42794GM	PG-DSO-14	42794GM
TLE42794E	PG-SSOP-14 exposed pad	42794E

Data Sheet 2 Rev. 1.1, 2008-10-09



Overview

Dimensioning Information on External Components

The input capacitor C_{l} is recommended for compensation of line influences. The output capacitor C_{Q} is necessary for the stability of the control loop.

Circuit Description

The control amplifier compares a reference voltage to a voltage that is proportional to the output voltage and drives the base of the series transistor via a buffer. Saturation control as a function of the load current prevents any oversaturation of the power element. The component also has a number of internal circuits for protection against:

- Overload
- Overtemperature
- Reverse polarity

Block Diagram

2 Block Diagram

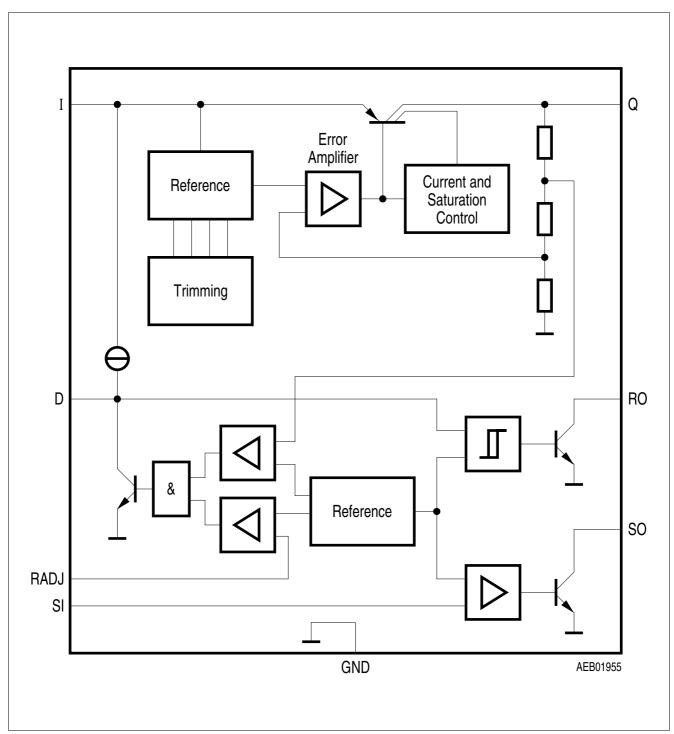


Figure 1 Block Diagram



Pin Configuration

3 Pin Configuration

3.1 Pin Assignment TLE42794G (PG-DSO-8)

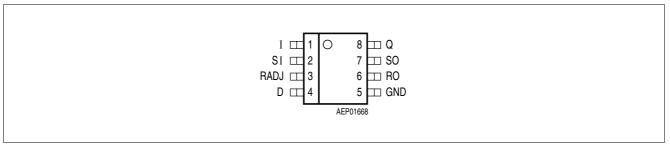


Figure 2 Pin Configuration (top view)

3.2 Pin Definitions and Functions TLE42794G (PG-DSO-8)

Pin	Symbol	Function
1	I	Input for compensating line influences, a capacitor to GND close to the IC terminals is recommended
2	SI	Sense Input connect the voltage to be monitored; connect to Q if the sense comparator is not needed
3	RADJ	Reset Threshold Adjust connect an external voltage divider to adjust reset threshold; connect to GND for using internal threshold
4	D	Reset Delay Timing connect a ceramic capacitor to GND for adjusting the reset delay time; leave open if the reset function is not needed
5	GND	Ground
6	RO	Reset Output open collector output; external pull-up resistor required, respecting values given in Item 5.6.5; leave open if the reset function is not needed
7	SO	Sense Output open collector output; external pull-up resistor required, respecting values given in Item 5.8.6; leave open if the sense comparator is not needed
8	Q	Output block to GND with a capacitor close to the IC terminals, respecting the values given for its capacitance C_Q and ESR in "Functional Range" on Page 9



Pin Configuration

3.3 Pin Assignment TLE42794GM (PG-DSO-14)

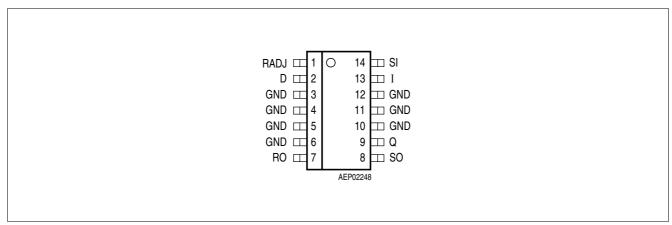


Figure 3 Pin Configuration (top view)

3.4 Pin Definitions and Functions TLE42794GM (PG-DSO-14)

Table 1

Pin	Symbol	Function
1	RADJ	Reset Threshold Adjust
		connect an external voltage divider to adjust reset threshold;
		connect to GND for using internal threshold
2	D	Reset Delay Timing
		connect a ceramic capacitor to GND for adjusting the reset delay time;
		leave open if the reset function is not needed
3, 4, 5, 6	GND	Ground
		connect all pins to PCB and heatsink area
7	RO	Reset Output
		open collector output; external pull-up resistor required, respecting values given in
		Item 5.6.5;
		leave open if the reset function is not needed
8	SO	Sense Output
		open collector output; external pull-up resistor required, respecting values given in
		Item 5.8.6;
-		leave open if the sense comparator is not needed
9	Q	Output
		block to GND with a capacitor close to the IC terminals, respecting the values given
		for its capacitance C_Q and ESR in the table "Functional Range" on Page 9
10, 11, 12	GND	Ground
-		connect all pins to PCB and heatsink area
13	I	Input
		for compensating line influences, a capacitor to GND close to the IC terminals is
		recommended
14	SI	Sense Input
		connect the voltage to be monitored;
		connect to Q if the sense comparator is not needed



Pin Configuration

3.5 Pin Assignment TLE42794E (PG-SSOP-14 exposed pad)

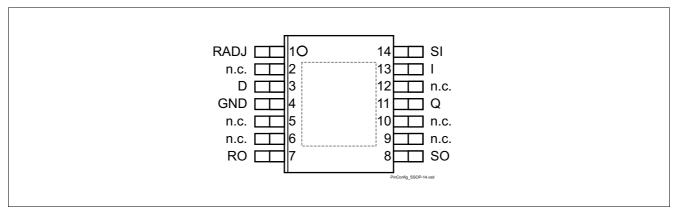


Figure 4 Pin Configuration (top view)

3.6 Pin Definitions and Functions TLE42794E (PG-SSOP-14 exposed pad)

Table 2

Pin	Symbol	Function
1	RADJ	Reset Threshold Adjust connect an external voltage divider to adjust reset threshold; connect to GND for using internal threshold
2, 5, 6	n.c.	not connected
3	D	Reset Delay Timing connect a ceramic capacitor to GND for adjusting the reset delay time; leave open if the reset function is not needed
4	GND	Ground connect all pins to PCB and heatsink area
7	RO	Reset Output open collector output; external pull-up resistor required, respecting values given in Item 5.6.4; leave open if the reset function is not needed
8	SO	Sense Output open collector output; external pull-up resistor required, respecting values given in Item 5.8.6; leave open if the sense comparator is not needed
9, 10, 12	n.c.	not connected
11	Q	Output block to GND with a capacitor close to the IC terminals, respecting the values given for its capacitance C_Q and ESR in the table "Functional Range" on Page 9
13	I	Input for compensating line influences, a capacitor to GND close to the IC terminals is recommended
14	SI	Sense Input connect the voltage to be monitored; connect to Q if the sense comparator is not needed



General Product Characteristics

4 General Product Characteristics

4.1 Absolute Maximum Ratings

Absolute Maximum Ratings 1)

-40 °C \leq T $_{\rm j}$ \leq 150 °C; all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol	Lin	nit Values	Unit	Conditions	
			Min.	Max.			
Input, S	Sense Input		-	 		<u>'</u>	
4.1.1	Voltage	V_1	-40	45	V	_	
Output	, Reset Output, Sense Output	<u> </u>	-			<u>'</u>	
4.1.2	Voltage	V_{Q}	-0.3	7	V	_	
Reset [Delay, Reset Threshold	-				1	
4.1.3	Voltage	V_{D}	-0.3	7	V	_	
Tempe	rature	1		-	1	1	
4.1.4	Junction Temperature	$T_{\rm j}$	-40	150	°C	_	
4.1.5	Storage Temperature	$T_{ m stg}$	-50	150	°C	_	
ESD A	osorption	, ,				1	
4.1.6	ESD Absorption	$V_{ESD,HBM}$	-2	2	kV	Human Body Model (HBM) ²⁾	
4.1.7		$V_{ESD,CDM}$	-500	500	V	Charge Device Model (CDM) ³⁾	
4.1.8			-750	750	V	Charge Device Model (CDM) ³⁾ a corner pins	

¹⁾ not subject to production test, specified by design

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

²⁾ ESD susceptibility Human Body Model "HBM" according to AEC-Q100-002 - JESD22-A114

³⁾ ESD susceptibility Charged Device Model "CDM" according to ESDA STM5.3.1



General Product Characteristics

4.2 Functional Range

Pos.	Parameter	Symbol	Lir	nit Values	Unit	Conditions
			Min.	Max.		
4.2.1	Input Voltage	V_1	5.5	45	V	_
4.2.2	Output Capacitor's Requirements	C_{Q}	10	_	μF	_1)
	for Stability	$ESR(C_{Q})$	_	3	Ω	_2)
4.2.3	Junction Temperature	T_{i}	-40	150	°C	_

¹⁾ the minimum output capacitance requirement is applicable for a worst case capacitance tolerance of 30%

Note: Within the functional range the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the related electrical characteristics table.

²⁾ relevant ESR value at f = 10 kHz



General Product Characteristics

4.3 Thermal Resistance

Pos.	Parameter	Symbol	L	imit Va	lue	Unit	Conditions	
			Min.	Тур.	Max.			
TLE427	794G (PG-DSO-8)	II.						
4.3.4	Junction to Soldering Point ¹⁾	R_{thJSP}	_	80	_	K/W	measured to pin 5	
4.3.5	Junction to Ambient ¹⁾	R_{thJA}	_	113	_	K/W	2)	
4.3.6			_	172	_	K/W	Footprint only ³⁾	
4.3.7			_	142	_	K/W	300mm ² heatsink area on PCB ³⁾	
4.3.8			_	136	_	K/W	600mm ² heatsink area on PCB ³⁾	
TLE427	794GM (PG-DSO-14)	+				-1	+	
4.3.9	Junction to Soldering Point ¹⁾	R_{thJSP}	_	27	_	K/W	measured to group of pins 3, 4, 5, 10, 11, 12	
4.3.10	Junction to Ambient ¹⁾	R_{thJA}	_	63	_	K/W	2)	
4.3.11			_	104	_	K/W	Footprint only ³⁾	
4.3.12			_	73	_	K/W	300mm ² heatsink area on PCB ³⁾	
4.3.13			_	65	_	K/W	600mm ² heatsink area on PCB ³⁾	
TLE427	794E (PG-SSOP-14 exposed page	d)						
4.3.14	Junction to Case ¹⁾	R_{thJC}	_	10	_	K/W	measured to Exposed Pad	
4.3.15	Junction to Ambient ¹⁾	R_{thJA}	_	47	_	K/W	2)	
4.3.16			_	145	_	K/W	Footprint only ³⁾	
4.3.17			_	63	-	K/W	300mm ² heatsink area on PCB ³⁾	
4.3.18			_	53	_	K/W	600mm ² heatsink area on PCB ³⁾	

¹⁾ not subject to production test, specified by design

²⁾ Specified R_{thJA} value is according to Jedec JESD51-2,-5,-7 at natural convection on FR4 2s2p board; The Product (Chip+Package) was simulated on a 76.2 x 114.3 x 1.5 mm³ board with 2 inner copper layers (2 x 70µm Cu, 2 x 35µm Cu). Where applicable a thermal via array under the exposed pad contacted the first inner copper layer.

³⁾ Specified R_{thJA} value is according to JEDEC JESD 51-3 at natural convection on FR4 1s0p board; The Product (Chip+Package) was simulated on a 76.2 × 114.3 × 1.5 mm³ board with 1 copper layer (1 x 70µm Cu).



5 Block Description and Electrical Characteristics

5.1 Voltage Regulator

The output voltage $V_{\rm Q}$ is controlled by comparing a portion of it to an internal reference and driving a PNP pass transistor accordingly. The control loop stability depends on the output capacitor $C_{\rm Q}$, the load current, the chip temperature and the poles/zeros introduced by the integrated circuit. To ensure stable operation, the output capacitor's capacitance and its equivalent series resistor ESR requirements given in the table "Functional Range" on Page 9 have to be maintained. For details see also the typical performance graph "Output Capacitor Series Resistor ESR(CQ) versus Output Current IQ" on Page 14. As the output capacitor also has to buffer load steps it should be sized according to the application's needs.

An input capacitor C_l is strongly recommended to compensate line influences. Connect the capacitors close to the component's terminals.

A protection circuitry prevent the IC as well as the application from destruction in case of catastrophic events. These safeguards contain an output current limitation, a reverse polarity protection as well as a thermal shutdown in case of overtemperature.

In order to avoid excessive power dissipation that could never be handled by the pass element and the package, the maximum output current is decreased at input voltages above V_1 = 22 V.

The thermal shutdown circuit prevents the IC from immediate destruction under fault conditions (e.g. output continuously short-circuited) by switching off the power stage. After the chip has cooled down, the regulator restarts. This leads to an oscillatory behaviour of the output voltage until the fault is removed. However, junction temperatures above 150 °C are outside the maximum ratings and therefore significantly reduce the IC's lifetime.

The TLE42794 allows a negative supply voltage. In this fault condition, small currents are flowing into the IC, increasing its junction temperature. This has to be considered for the thermal design, respecting that the thermal protection circuit is not operating during reverse polarity conditions.

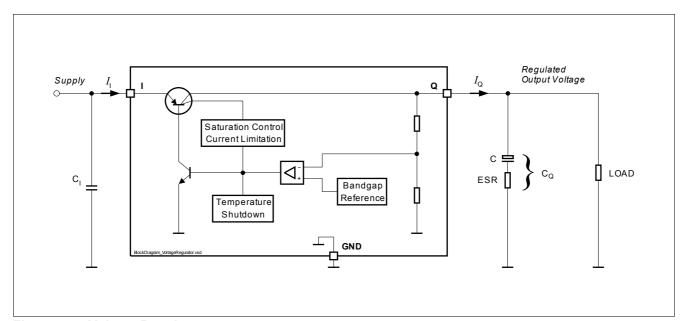


Figure 5 Voltage Regulator



5.2 Electrical Characteristics Voltage Regulator

Electrical Characteristics Voltage Regulator

 $V_{\rm I}$ = 13.5 V, -40 °C \leq $T_{\rm j} \leq$ 150 °C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions	
			Min.	Тур.	Max.			
5.2.1	Output Voltage	V_{Q}	4.9	5.0	5.1	V	100 μ A < $I_{\rm Q}$ < 100 mA 6 V < $V_{\rm I}$ < 18 V	
5.2.2	Output Current Limitation	$I_{Q,max}$	150	200	500	mA	$V_{\rm Q}$ = 4.8V	
5.2.3	Load Regulation steady-state	$\Delta V_{ m Q,load}$	-30	-15	_	mV	$I_{\rm Q}$ = 5 mA to 100 mA $V_{\rm I}$ = 6 V	
5.2.4	Line Regulation steady-state	$\Delta V_{ m Q,line}$	_	10	40	mV	$V_{\rm I}$ = 6 V to 32 V $I_{\rm Q}$ = 5 mA	
5.2.5	Dropout Voltage ¹⁾ $V_{dr} = V_{l} - V_{Q}$	V_{dr}	_	250	500	mV	I _Q = 100 mA	
5.2.6	Overtemperature Shutdown Threshold	$T_{j,sd}$	151	_	200	°C	$T_{\rm j}$ increasing ²⁾	
5.2.7	Overtemperature Shutdown Threshold Hysteresis	$T_{ m j,sdh}$	-	15	_	°C	$T_{\rm j}$ decreasing ²⁾	
5.2.8	Power Supply Ripple Rejection ²⁾	PSRR	_	70	-	dB	f_{ripple} = 100 Hz V_{ripple} = 0.5 Vpp	

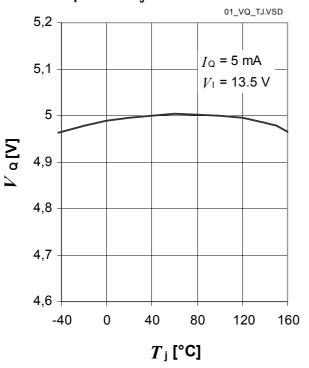
¹⁾ measured when the output voltage $V_{\rm Q}$ has dropped 100mV from the nominal value obtained at $V_{\rm I}$ = 13.5V

²⁾ not subject to production test, specified by design

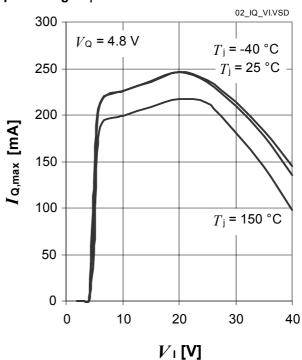


5.3 Typical Performance Characteristics Voltage Regulator

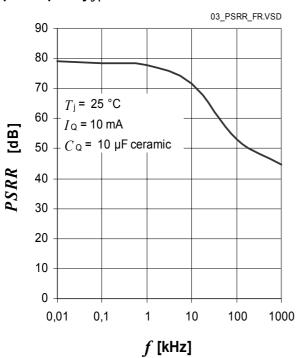
Output Voltage $V_{\rm Q}$ versus Junction Temperature $T_{ m J}$



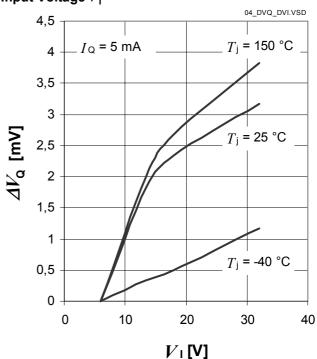
Output Current $I_{\rm Q}$ versus Input Voltage $V_{\rm I}$



Power Supply Ripple Rejection PSRR versus ripple frequency $f_{\rm r}$

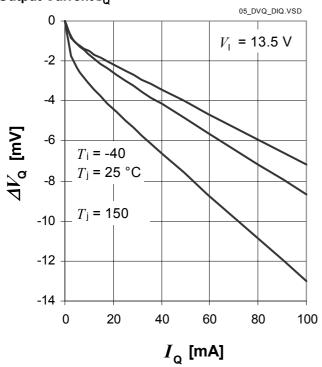


Line Regulation $\Delta V_{ m Q,line}$ versus Input Voltage $V_{ m I}$

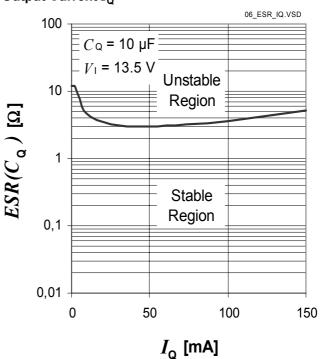




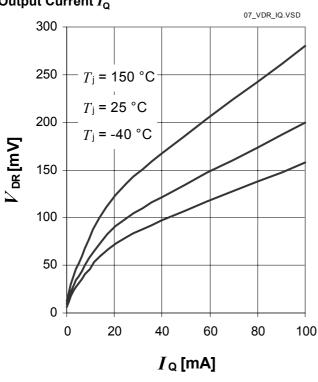
Load Regulation $\Delta V_{\mathrm{Q,load}}$ versus Output Current I_{O}



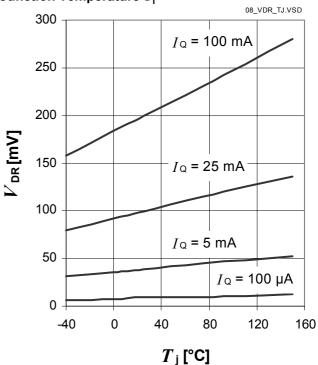
Output Capacitor Series Resistor $ESR(C_{\rm Q})$ versus Output Current $I_{\rm Q}$



Dropout Voltage V_{dr} versus Output Current I_{Q}



Dropout Voltage $V_{ m dr}$ versus Junction Temperature $T_{ m i}$





5.4 Current Consumption

Electrical Characteristics Voltage Regulator

 $V_{\rm I}$ = 13.5 V, -40 °C \leq $T_{\rm j} \leq$ 150 °C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol		Limit Values			Conditions
			Min.	Тур.	Max.		
5.4.1	Current Consumption $I_q = I_Q - I_1$	I_{q}	-	210	280	μΑ	$I_{\rm Q}$ = 100 µA $T_{\rm j}$ = 25 °C
5.4.2			_	240	300	μΑ	$I_{\rm Q}$ = 100 μA $T_{\rm j}$ ≤ 85 °C
5.4.3			_	0.7	1	mA	$I_{\rm Q}$ = 10 mA
5.4.4			-	3.5	8	mA	$I_{\rm Q}$ = 50 mA

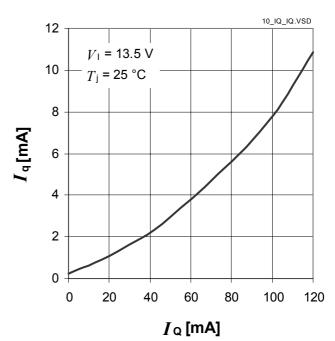


5.5 Typical Performance Characteristics Current Consumption

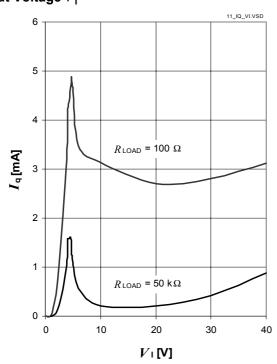
Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm Q}$ ($I_{\rm Q}$ low)

09_IQ_IQ_IQLOW.VSD 1,6 V_1 = 13.5 V 1,4 $T_j = 25 \, ^{\circ}\text{C}$ 1,2 1 0,8 0,6 0,4 0,2 0 5 10 20 0 15 25 $I_{\rm Q} [{\rm mA}]$

Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm Q}$



Current Consumption $I_{\rm q}$ versus Input Voltage $V_{\rm I}$





5.6 Reset Function

The reset function provides several features:

Output Undervoltage Reset:

An output undervoltage condition is indicated by setting the Reset Output RO to "low". This signal might be used to reset a microcontroller during low supply voltage.

Power-On Reset Delay Time:

The power-on reset delay time $t_{\rm rd}$ allows a microcontoller and oscillator to start up. This delay time is the time frame from exceeding the reset switching threshold $V_{\rm RT}$ until the reset is released by switching the reset output "RO" from "low" to "high". The power-on reset delay time $t_{\rm rd}$ is defined by an external delay capacitor $C_{\rm D}$ connected to pin D charged by the delay capacitor charge current $I_{\rm D,ch}$ starting from $V_{\rm D}$ = 0 V.

If the application needs a power-on reset delay time $t_{\rm rd}$ different from the value given in **Item 5.6.7**, the delay capacitor's value can be derived from the specified values in **Item 5.6.7** and the desired power-on delay time:

$$C_D = \frac{t_{rd, new}}{t_{rd}} \times 47 nF$$

with

- C_D: capacitance of the delay capacitor to be chosen
- t_{rd.new}: desired power-on reset delay time
- t_{rd}: power-on reset delay time specified in this datasheet

For a precise calculation also take the delay capacitor's tolerance into consideration.

Reset Reaction Time:

The reset reaction time avoids that short undervoltage spikes trigger an unwanted reset "low" signal. The reset reaction rime $t_{\rm rr}$ considers the internal reaction time $t_{\rm rr,int}$ and the discharge time $t_{\rm rr,d}$ defined by the external delay capacitor $C_{\rm D}$ (see typical performance graph for details). Hence, the total reset reaction time becomes:

$$t_{rr} = t_{rd, int} + t_{rr, d}$$

with

- t_{rr}: reset reaction time
- t_{rr.int}: internal reset reaction time
- t_{rr.d}: reset discharge



Reset Output Pull-Up Resistor R_{RO} :

The Reset Output RO is an open collector output requiring an external pull-up resistor. In **Table "Electrical** Characteristics Reset Function" on Page 20 a minimum value for the external resistor $R_{\rm RO}$ is given. Keep in mind to stay within the values specified for the Reset Output RO in **Table 4.1 "Absolute Maximum Ratings" on** Page 8

Reset Adjust Function

The undervoltage reset switching threshold can be adjusted according to the application's needs by connecting an external voltage divider ($R_{\rm ADJ1}$, $R_{\rm ADJ2}$) at pin RADJ. For selecting the default threshold connect pin RADJ to GND.

When dimensioning the voltage divider, take into consideration that there will be an additional current constantly flowing through the resistors.

With a voltage divider connected, the reset switching threshold $V_{\rm RT,new}$ is calculated as follows:

$$V_{RT, \text{ new}} = \frac{R_{ADJ, 1} + R_{ADJ, 2}}{R_{ADJ, 2}} \times V_{RADJ, \text{ th}}$$

with

- $V_{\rm RT,new}$: the desired new reset switching threshold
- $R_{\rm ADJ1}$, $R_{\rm ADJ2}$: resistors of the external voltage divider
- $V_{\rm RADJ,th}$: reset adjust switching threshold given in Table "Electrical Characteristics Reset Function" on Page 20

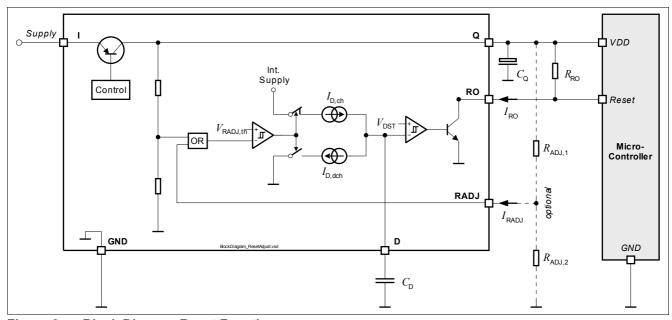


Figure 6 Block Diagram Reset Function



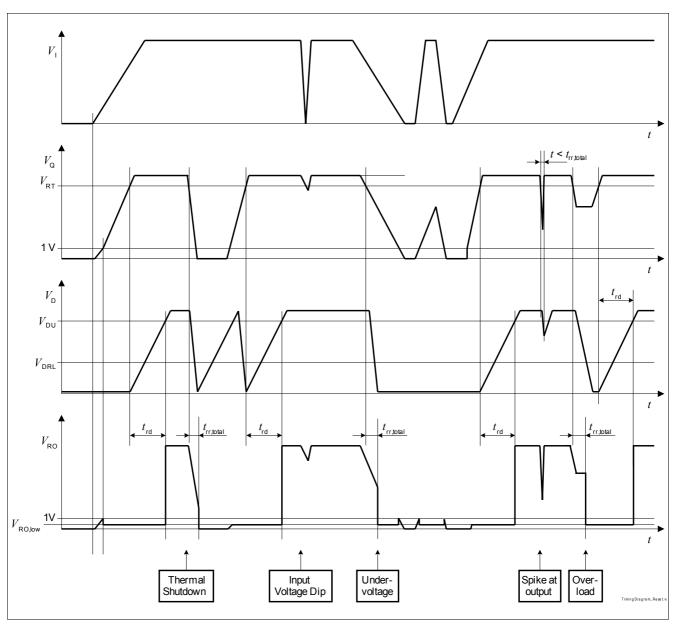


Figure 7 Timing Diagram Reset



Electrical Characteristics Reset Function

 $V_{\rm I}$ = 13.5 V, -40 °C ≤ $T_{\rm j}$ ≤ 150 °C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
Output	Undervoltage Reset		-	<u> </u>	-		
5.6.1	Default Output Undervoltage Reset Switching Thresholds	V_{RT}	4.5	4.65	4.8	V	V_{Q} decreasing
Output	Undervoltage Reset Threshold Ad	justment					L
5.6.2	Reset Adjust Switching Threshold	$V_{RADJ,th}$	1.26	1.35	1.44	V	$3.5 \text{ V} \le V_{Q} < 5 \text{ V}$
5.6.3	Reset Adjustment Range ¹⁾	$V_{\rm RT,range}$	3.50	_	4.65	V	_
Reset (Output RO	, ,		"	"		-
5.6.4	Reset Output Low Voltage	$V_{RO,low}$	_	0.1	0.4	V	$\begin{array}{l} \text{1 V} \leq V_{\text{Q}} \leq V_{\text{RT}} \\ \text{external} \\ R_{\text{RO,ext}} = \text{10 k}\Omega \end{array}$
5.6.5	Reset Output External Pull-up Resistor to $V_{\rm Q}$	$R_{RO,ext}$	10	-	-	kΩ	$1 \text{ V} \leq V_{\text{Q}} \leq V_{\text{RT}};$ $V_{\text{RO}} \leq 0.4 \text{ V}$
Reset I	Delay Timing		•				
5.6.6	Delay Pin Output Voltage	V_{D}	_	_	5	V	_
5.6.7	Power On Reset Delay Time	$t_{\rm rd}$	17	28	39	ms	$C_{\rm D}$ = 100 nF
5.6.8	Upper Delay Switching Threshold	V_{DU}	_	1.8	_	V	_
5.6.9	Lower Delay Switching Threshold	V_{DL}	_	0.45	_	V	-
5.6.10	Delay Capacitor Charge Current	$I_{D,ch}$	-	6.5	_	μΑ	<i>V</i> _D = 1 V
5.6.11	Delay Capacitor Reset Discharge Current	$I_{D,dch}$	-	70	_	mA	<i>V</i> _D = 1 V
5.6.12	Delay Capacitor Discharge Time	$t_{rr,d}$	_	1.9	3	μs	Calculated Value: $t_{\rm rr,d} = C_{\rm D}^* (V_{\rm DU} - V_{\rm DL}) / I_{\rm D,dch}$ $C_{\rm D} = 100~{\rm nF}$
5.6.13	Internal Reset Reaction Time	$t_{\rm rr,int}$	_	3	7	μs	$C_{\rm D}$ = 0 nF ²⁾
5.6.14	Reset Reaction Time	$t_{ m rr,total}$	-	4.9	10	μs	Calculated Value: $t_{\text{rr,total}} = t_{\text{rr,int}} + t_{\text{rr,d}}$ $C_{\text{D}} = 100 \text{ nF}$

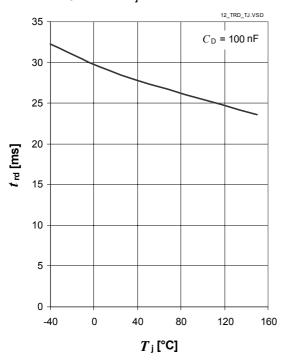
¹⁾ $V_{\rm RT}$ is scaled linearly, in case the Reset Switching Threshold is modified

²⁾ parameter not subject to production test; specified by design



5.7 Typical Performance Characteristics Reset

Power On Reset Delay Time $t_{\rm rd}$ versus Junction Temperature $T_{\rm j}$





5.8 Early Warning Function

The additional sense comparator provides an early warning function: Any voltage (e.g. the input voltage) can be monitored, an undervoltage condition is indicated by setting the comparator's output to low.

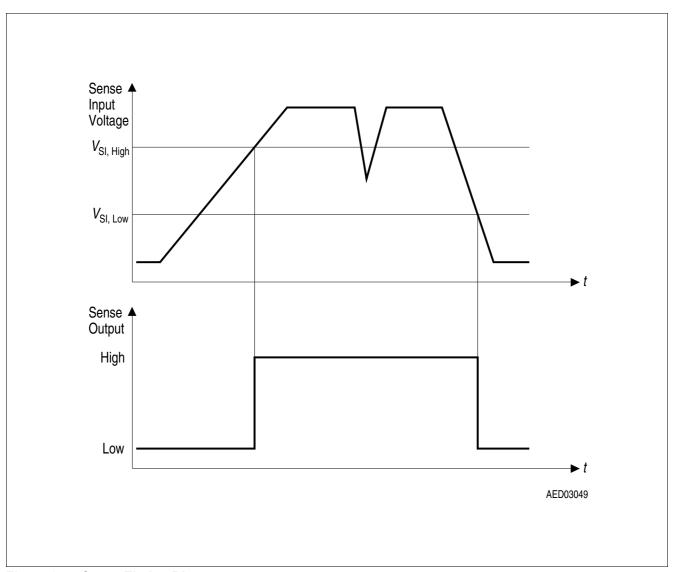


Figure 8 Sense Timing Diagram

Electrical Characteristics Early Warning Function

 $V_{\rm I}$ = 13.5 V, -40 °C ≤ $T_{\rm j}$ ≤ 150 °C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
Sense	Comparator Input			<u> </u>			1
5.8.1	Sense Threshold High	$V_{SI,high}$	1.24	1.31	1.38	V	_
5.8.2	Sense Threshold Low	$V_{SI,low}$	1.16	1.22	1.28	V	_
5.8.3	Sense Switching Hysteresis	$V_{SI,hy}$	20	90	160	mV	_
5.8.4	Sense Input Current	I_{SI}	-1	-0.1	1	μΑ	_



Electrical Characteristics Early Warning Function

 $V_{\rm I}$ = 13.5 V, -40 °C ≤ $T_{\rm j}$ ≤ 150 °C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Pos.	Parameter	Symbol	1	Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
Sense	Comparator Output		- 1	1	1	"	1
5.8.5	Sense Output Low Voltage	$V_{ m SO,low}$	_	0.1	0.4	V	$V_{\rm SI} < V_{\rm SI,low}$ $V_{\rm I} > 5.5 {\rm V}$ $R_{\rm SO,ext} = 10 {\rm k}\Omega$
5.8.6	Sense Output External Pull-up Resistor to $V_{\rm Q}$	$R_{ m SO,ext}$	10	_	_	kΩ	$V_{\rm I} > 5.5 \ { m V}$ $V_{\rm SO} \le 0.4 \ { m V}$

Data Sheet 23 Rev. 1.1, 2008-10-09

Package Outlines

6 Package Outlines

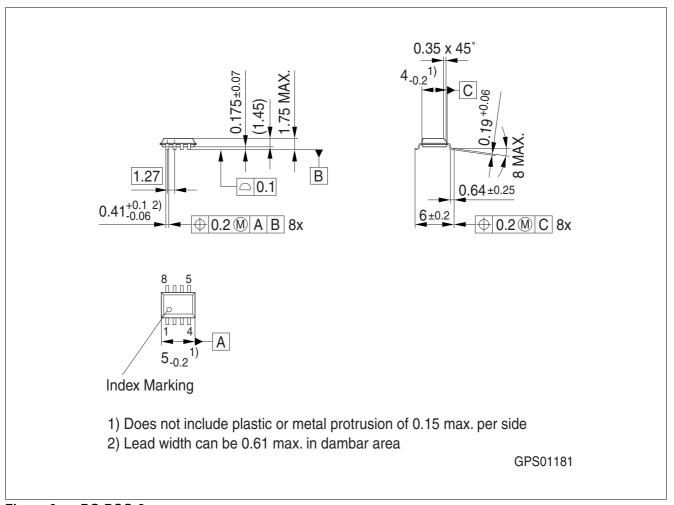


Figure 9 PG-DSO-8



Package Outlines

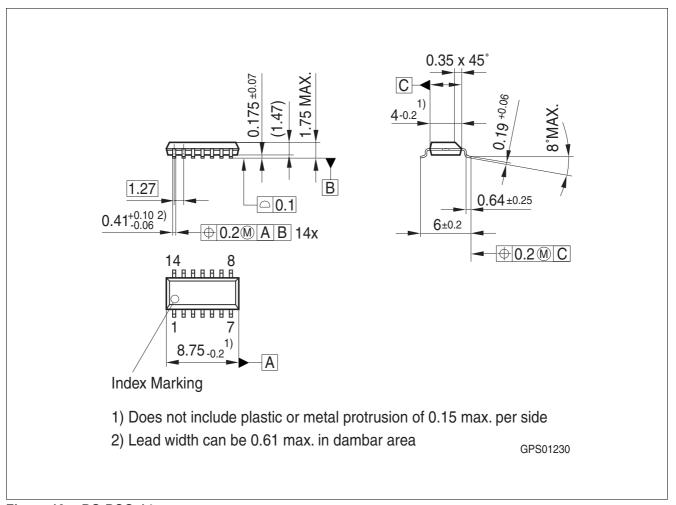


Figure 10 PG-DSO-14



Package Outlines

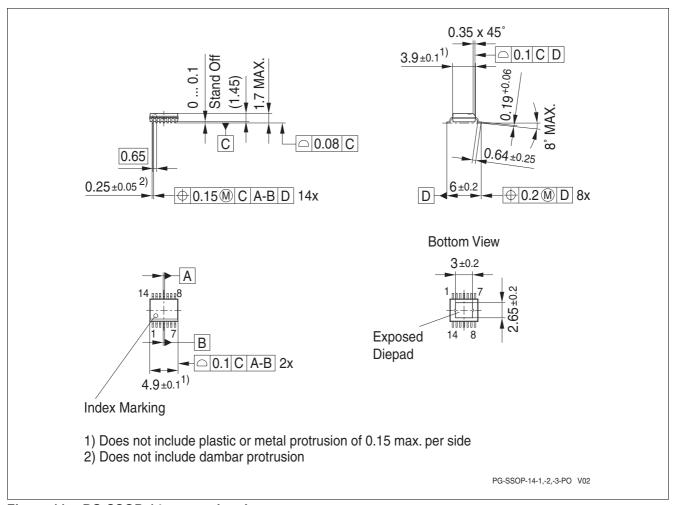


Figure 11 PG-SSOP-14 exposed pad

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).



Revision History

7 Revision History

Revision	Date	Changes
1.1	2008-10-09	package version TLE42794E in PG-SSOP-14 exposed pad and all related information added
		In "Overview" on Page 2 package graphic for PG-SSOP-14 exposed pad and product name "TLE42794E" added
		In Chapter 3 "Pin Assignment TLE42794E (PG-SSOP-14 exposed pad)" on Page 7 and "Pin Definitions and Functions TLE42794E (PG-SSOP-14 exposed pad)" on Page 7 added
		In "Thermal Resistance" on Page 10 values for TLE42794E added
		In "Package Outlines" on Page 24 outlines for TLE4279E added
1.0	2008-09-19	initial version data sheet

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